

- Excels in sorting fragile GaAs and MEMS devices
- Available for up to 300mm wafers
- Picks die as small as 200  $\mu\text{m}$  square
- Waffle pack, Gel-Pak® and film frame output
- Underside and facet inspection options
- Die inverter option
- Throughput of 500-1200 UPH (product, process dependent)
- Quick change over
- Optional non-surface contact operation for MEMS, air-bridge GaAs, optical and other sensitive devices

# DE35-ST Semi-Automatic Pick & Place System

## Quick Change, Flexible Die Sorter

The DE35-ST semi-automatic die pick and place system is a straight-forward, low cost machine for picking die from sawn or scribed wafers mounted on adhesive film.

Die can be placed into waffle packs, Gel-Pak®, film frame, or directly onto substrates.

Optimized for small lot production, the DE35-ST is simple to learn and use. No hand tools are needed for die size changeover. Setup and option information is preserved in user selectable recipes.

Hundreds of catalog waffle pack parameters are pre-programmed with space for hundreds more user programmed parameters.

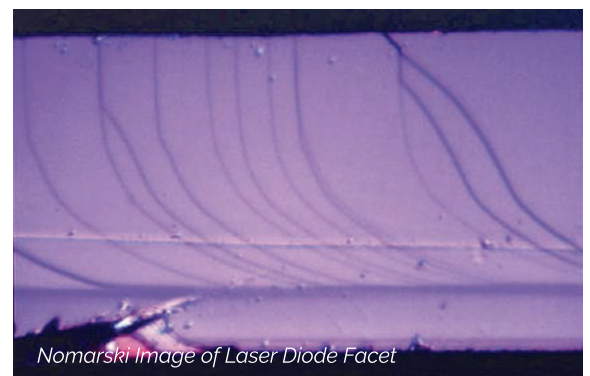
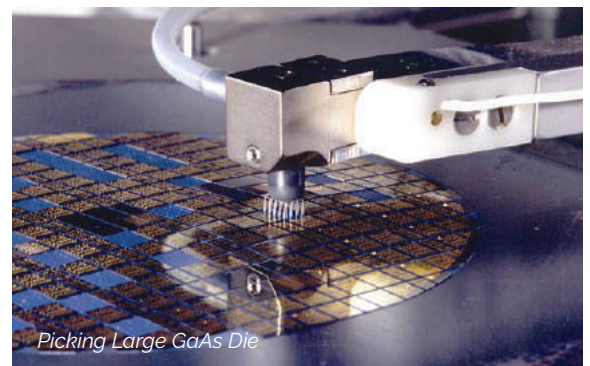
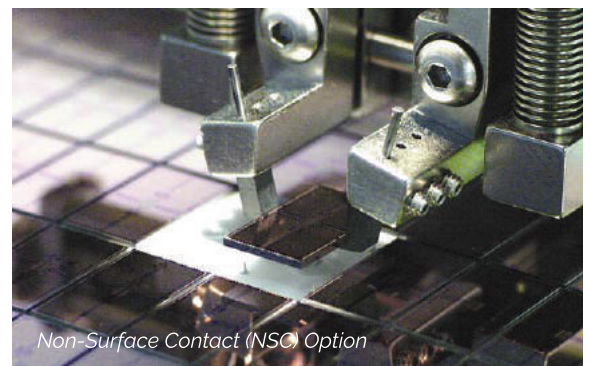
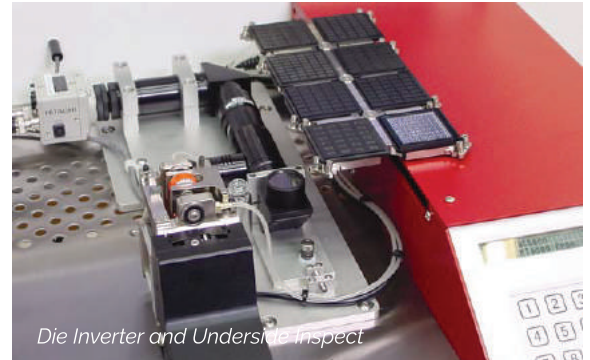
Waffle pack pockets for die placement are automatically selected. Manual selection using the keypad arrow keys enables completion of partially filled waffle packs.

## Specifications

Smallest Die Size: 200  $\mu$ m  
Largest Die Size: >25 mm  
Largest Wafer: 200 mm, 300 mm special order  
Die Placement:  $\pm$  120  $\mu$ m  
Die Surface Load: <10 gf  
Throughput: 500 to 1200 UPH

Electrical: 110-240 VAC, 50-60 Hz,  
Single phase  
Air: 275 k Pa to 550 kPa (40-80 psig)  
Vacuum: -65 kPa (20 in Hg)

Weight: 93 kg, 205 lbs  
Width: 1120 mm, 44 in  
Depth: 840 mm, 33 in  
Height 660 mm, 26 in



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